

**1. Scope :**

This specification applies to P/N silicon TVS diode chips,  
Device NO. SD-141C0

**2. Structure :**

- 2-1. Planar type : P/N Diode.
- 2-2. Electrodes :  
Top side : Aluminum alloy.  
Back side : Gold layer.

**3. Size :**

- 3-1. Chip size : 47.2 mils x 35.4 mils (1.200 mm x 0.900 mm ).
- 3-2. Chip thickness :  $5.9 \pm 1.0$  mils ( $0.150 \pm 0.0254$  mm )
- 3-3. Bonding pad : 42.5 mils x 30.7 mils (1.080 mm x 0.780 mm).
- 3-4. Pattern drawing : Refer to the attached drawing.

**4. Electrical characteristics (Ta = 25 °C)**

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse Current	$I_R$	$V_R=33V$ $E_e=0mW/cm^2$			600	nA
Reverse Breakdown Voltage	$V_{(BR)}$	$I_R=5mA$ $E_e=0mW/cm^2$	38		42	V
Forward Voltage	$V_f$	$I_F=10mA$ $E_e=0mW/cm^2$			1.2	V

